+357 96 030922
info@marketpublishers.com

Global Wafer Thinning Grinding Wheels Market 2025 by Manufacturers, Regions, Type and Application, Forecast to 2031

https://marketpublishers.com/r/G6F8770D7BF4EN.html
Date: September 2025
Pages: 122
Price: US$ 3,132.00 (Single User License)
ID: G6F8770D7BF4EN

Abstracts

According to our (Global Info Research) latest study, the global Wafer Thinning Grinding Wheels market size was valued at US$ 456 million in 2024 and is forecast to a readjusted size of USD 780 million by 2031 with a CAGR of 7.2% during review period.

In this report, we will assess the current U.S. tariff framework alongside international policy adaptations, analyzing their effects on competitive market structures, regional economic dynamics, and supply chain resilience.

A Wafer Thinning Grinding Wheel is a specialized abrasive tool used in semiconductor manufacturing to reduce the thickness of silicon wafers while maintaining their structural integrity and surface quality. This process, known as wafer thinning, is critical for producing ultra-thin wafers used in advanced electronic devices like smartphones, microprocessors, and memory chips. The grinding wheel typically features a diamond abrasive layer, ensuring precision, minimal damage, and high efficiency. Its design and material composition are optimized to handle the delicate nature of wafers while achieving the required thickness and flatness.

The global key manufacturers of Thinning Grinding Wheels include DISCO, Saint-Gobain, TOKYO SEIMITSU, EHWA DIAMOND, Asahi Diamond Industrial Co.,Ltd., SAESOL, KINIK COMPANY, A.L.M.T. Corp., Sinomach-pi, Suzhou Sail Science & Technology Co., Ltd., etc. In 2024, the global top 10 players had a share approximately 68.0% in terms of revenue.
Asia-Pacific stands as the dominant region in this market, accounting for about 78% of global consumption. This is attributed to the region's robust semiconductor manufacturing infrastructure, with countries like China, Taiwan, and South Korea

+357 96 030922
info@marketpublishers.com

leading in production capacities.?

In terms of wafer size, 300mm wafers constitute the largest segment, representing approximately 80% of the market share. The shift towards larger wafer sizes is driven by the industry's pursuit of higher yield and cost efficiency, as larger wafers allow for the production of more chips per unit area.?

Market Driving Factors

Advancements in Semiconductor Technology: The continuous evolution of semiconductor devices, including the adoption of 5G, AI, and IoT technologies, necessitates the production of smaller, more efficient chips. This drives the demand for precise wafer thinning to achieve the desired performance metrics.

Technological Innovations in Grinding Tools: Developments in grinding wheel materials and bonding techniques have enhanced grinding efficiency and tool longevity. Innovations such as ultra-fine diamond abrasives and resin-bonded wheels contribute to improved surface finishes and reduced material wastage.

Expansion of Semiconductor Fabrication Facilities: Significant investments in new fabrication plants by major semiconductor manufacturers are propelling the need for high-precision grinding wheels to meet the increasing production demands.

Growing Demand for 300mm Wafers: The industry's shift towards larger wafer sizes for better yield and cost efficiency is increasing the demand for thinning grinding wheels tailored for 300mm wafers.

Market Restraints

High Initial Investment Costs: The specialized equipment and technology required for wafer grinding are capital-intensive, posing a barrier for smaller semiconductor manufacturers or those in emerging markets.

Technical Complexity: The wafer grinding process demands skilled operators and precise control to avoid damaging the delicate wafers. Inadequate handling can lead to increased production costs and reduced yields.

Supply Chain Challenges: Fluctuations in the availability and cost of raw materials, such as diamond abrasives, impact the production and pricing of grinding wheels.

+357 96 030922
info@marketpublishers.com

Additionally, global supply chain issues can affect the timely availability of these specialized tools.

Environmental and Regulatory Constraints: Stringent environmental regulations and the need for sustainable manufacturing practices are compelling companies to develop eco-friendly grinding solutions, which may require additional research and development investments.

This report is a detailed and comprehensive analysis for global Wafer Thinning Grinding Wheels market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Wafer Thinning Grinding Wheels market size and forecasts, in consumption value ($ Million), sales quantity (K Units), and average selling prices (US$/Unit), 2020-2031

Global Wafer Thinning Grinding Wheels market size and forecasts by region and country, in consumption value ($ Million), sales quantity (K Units), and average selling prices (US$/Unit), 2020-2031

Global Wafer Thinning Grinding Wheels market size and forecasts, by Type and by Application, in consumption value ($ Million), sales quantity (K Units), and average selling prices (US$/Unit), 2020-2031

Global Wafer Thinning Grinding Wheels market shares of main players, shipments in revenue ($ Million), sales quantity (K Units), and ASP (US$/Unit), 2020-2025

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries
To assess the growth potential for Wafer Thinning Grinding Wheels
To forecast future growth in each product and end-use market
To assess competitive factors affecting the marketplace

+357 96 030922
info@marketpublishers.com

This report profiles key players in the global Wafer Thinning Grinding Wheels market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include DISCO, Saint-Gobain, TOKYO SEIMITSU, EHWA DIAMOND, Asahi Diamond Industrial Co.,Ltd., SAESOL, KINIK COMPANY, A.L.M.T. Corp., Sinomach-pi, Suzhou Sail Science & Technology Co., Ltd., etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Wafer Thinning Grinding Wheels market is split by Type and by Application. For the period 2020-2031, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Vitrified Bond

Resinoid Bond

Others

Market segment by Application

Rough Grinding

Fine Grinding

Major players covered

DISCO

+357 96 030922
info@marketpublishers.com

Saint-Gobain

TOKYO SEIMITSU

EHWA DIAMOND

Asahi Diamond Industrial Co.,Ltd.

SAESOL

KINIK COMPANY

A.L.M.T. Corp.

Sinomach-pi

Suzhou Sail Science & Technology Co., Ltd.

Zhengzhou Qisheng

Nanjing Sanchao

Market segment by region, regional analysis covers

North America (United States, Canada, and Mexico)
Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)
Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)
South America (Brazil, Argentina, Colombia, and Rest of South America)
Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe Wafer Thinning Grinding Wheels product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of Wafer Thinning Grinding Wheels, with

+357 96 030922
info@marketpublishers.com

price, sales quantity, revenue, and global market share of Wafer Thinning Grinding Wheels from 2020 to 2025.

Chapter 3, the Wafer Thinning Grinding Wheels competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the Wafer Thinning Grinding Wheels breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2020 to 2031.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2020 to 2031.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2020 to 2025.and Wafer Thinning Grinding Wheels market forecast, by regions, by Type, and by Application, with sales and revenue, from 2026 to 2031.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of Wafer Thinning Grinding Wheels.

Chapter 14 and 15, to describe Wafer Thinning Grinding Wheels sales channel, distributors, customers, research findings and conclusion.

+357 96 030922
info@marketpublishers.com

Contents

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

3 COMPETITIVE ENVIRONMENT: WAFER THINNING GRINDING WHEELS BY MANUFACTURER

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

List Of Tables

LIST OF TABLES

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

List Of Figures

LIST OF FIGURES

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

I would like to order

Product name: Global Wafer Thinning Grinding Wheels Market 2025 by Manufacturers, Regions, Type and Application, Forecast to 2031

Product link: https://marketpublishers.com/r/G6F8770D7BF4EN.html

Price: US$ 3,132.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:
info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page https://marketpublishers.com/r/G6F8770D7BF4EN.html